

- Status Indicating LED on X4 Series
- UL, CSA, and CE

Solid state I/O switching modules deliver an electrically clean, photo-isolated, noise-free "output" interface from logic level control systems to external loads such as motors, valves, solenoids, etc. -- or an "input" interface from the load or sensors to microprocessor or computer-based logic level systems. Designed for long, reliable service in demanding industrial environments.

INPUT SPECIFICATIONS

	IDC5 (S)MIDC5 X4IDC5	IDC15 (S)MIDC15 X4IDC15	IDC24 (S)MIDC24 X4IDC24	IDC5D (S)MIDC5D X4IDC5D	IDC15D (S)MIDC15D X4IDC15D	IDC24D (S)MIDC24D X4IDC24D
Nominal Input Voltage [Vdc]	24	24	24	24	24	24
Min. Input Voltage [Vdc]	10	10	10	3.3	3.3	3.3
Max. Input Voltage [Vdc]	36	36	36	32	32	32
Nominal Input Resistance [ohm]	-	-	-	1K	1K	1K
Max. Input Current [mAdc]	16	16	16	32	32	32
Drop Out Current [mAdc]	1.0	1.0	1.0	1.0	1.0	1.0
Allowable Off-State Current [mAdc]	1.0	1.0	1.0	1.0	1.0	1.0
Allowable Off-State Voltage [Vdc]	2.0	2.0	2.0	2.0	2.0	2.0

OUTPUT SPECIFICATIONS

Nominal Logic Voltage [Vdc]	5	15	24	5	15	24
Min. Logic Voltage [Vdc] (X4 Series)	1.5 (3)	8.5 (10)	16.5 (18)	1.5 (3)	8.5 (10)	16.5 (18)
Max. Logic Voltage [Vdc] (X4 Series)	6.0 (7)	18.5 (20)	30.5 (32)	5.5 (7)	18.5 (20)	30.5 (32)
Typical Logic Supply Current [mAdc]	10	10	10	10	10	10
Max. Logic Supply Current [mAdc]	18	16	14	18	16	14
Max. Logic Supply Leakage Current [µAdc]	10	10	10	10	10	10
Max. Output Voltage [Vdc]	30	30	30	30	30	30
Max. Output Current [mAdc]	50	50	50	50	50	50
Max. Output Leakage Current [µAdc]	10	10	10	10	10	10
Max. Output Voltage Drop [mVdc]	200	200	200	200	200	200
Max. Turn-On Time [µsec] ①	1000	1000	1000	300	300	300
Max. Turn-Off Time [µsec] ①	1000	1000	1000	600	600	600

GENERAL NOTES

① At nominal voltage and room temperature.

© 2007 CRYDOM Inc., Specifications subject to change without notice.

GENERAL SPECIFICATIONS

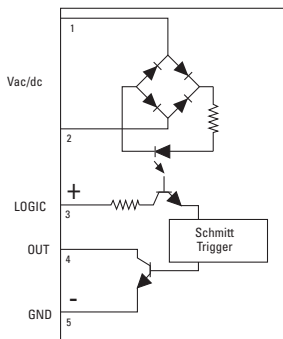
Operating temperature range	-30 to +80° C
Storage temperature range	-40 to +100° C
Isolation	4,000 Vrms
Capacitance input to output	8 pF
Package Color	White

APPLICATION NOTES

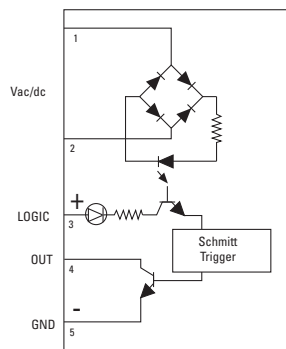
- Do not install or remove modules in live (electrically hot) circuits. High voltage may be present.
- An externally located commutating diode must be installed across inductive loads
- I/O module boards also available

WIRING & MECHANICAL DIAGRAMS

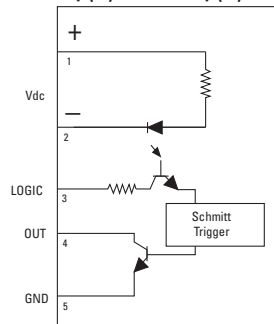
**IDC5, IDC15, IDC24
(S)MIDC5, MIDC15, MIDC24**



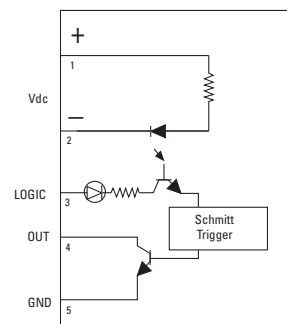
X4IDC5, X4IDC15, X4IDC24



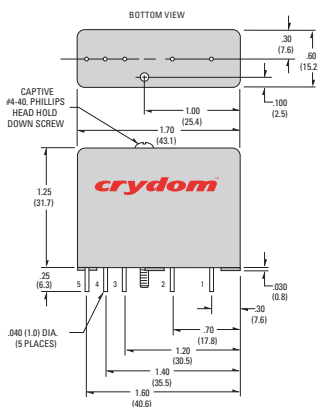
**IDC5D, IDC15D, IDC24D
(S)MIDC5D, (S)MIDC15D, (S)MIDC24D**



X4IDC5D, X4IDC15D, X4IDC24D

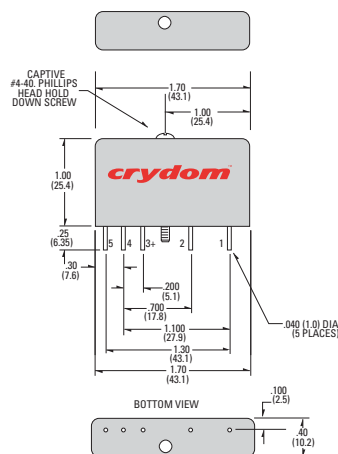


Standard Series, IDC

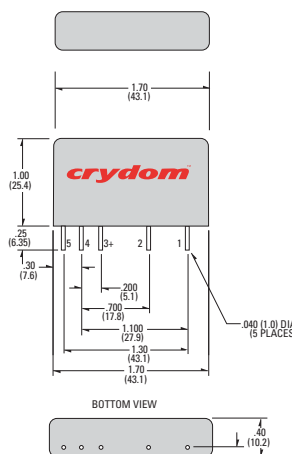


MINI-PACK Series, (S)MIDC

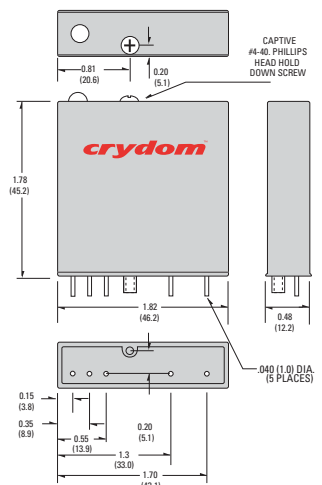
SM Prefix



M Prefix



X4 Series, X4IDC



All dimensions are in inches (millimeters)

© 2007 CRYDOM Inc., Specifications subject to change without notice.

ANNEX – ENVIRONMENTAL INFORMATION:

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People's Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

Part Name	Toxic or hazardous Substance and Elements					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr (VI))	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Semiconductor die	X	O	O	O	O	O
Solder	X	O	O	O	O	O

附件 - 环保信息:

此附件所标示的包括电子信息产品污染图标的环保信息符合中华人民共和国电子行业标准 **SJ/T11364 - 2006**, 电子信息产品污染控制标识要求

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr (VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
半导体芯片	X	O	O	O	O	O
焊接点	X	O	O	O	O	O

